Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	911	174/258.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:03
L7	66	I6 and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:07
L8	8	I6 and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:09
L9	24	174/260.ccls. and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:15
L10	0	174/265.ccls. and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:15
L11	18	174/255.ccls. and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:23
L12	8	174/258.ccls. and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:23
L13	6	174/259.ccls. and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:27

L14	10	"174"/$.ccls. and ceramic and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator) and thick$4 and crysta$4 and diameter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:16
L15	5	"361/748.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:19
L16	5	"361/762.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:20
L17	2	"361/763.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:20
L18	13	"361/764.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:26
L19	5	"361/765.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:27
L20	29	"361/719.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:27
L21	29	"361/719.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or (heat-sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:30

L22	18	"361/720.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or (heat-sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:39
L23	7	"361/687.ccls. and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or (heat-sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:40
L24	206	"361"/$.ccls. and substrate and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or (heat-sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:51
L25	148	l24 not (15 16 17 18 19 20 21 22 23)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:53
L26	1081	"257"/$.ccls. and substrate and (ceramic or ALN or alum$4) and copper and (metal adj (layer or plane)) and (chip or semiconductor adj device) and ((heat adj sink) or (heat-sink) or radiator)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:51
L27	921	l26 not (15 16 17 18 19 20 21 22 23 24)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:58
L28	24	l27 and pure adj copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 13:53
L35	17	("5883428" "6111322" "6569756" "6891247" "20020070443" "5998000" "4926242" "6400573" "6519154" "6651736" "6455930" "5981085" "5931222" "6911728" "6667548" "6300167" "5881944").pn. and ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 14:55

L36	813650	l35 abd copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 14:55
L37	15	l35 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 16:56
L38	15	l35 and (wir$3 near "5" copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 14:56
L39	11	l38 and (metal adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 14:57
L40	5	l39 and (ALN)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 14:58
L41	5	l40 and thick$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 16:55
L42	2	"6353189".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 15:06
L43	4	("6483185" "6310775").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 15:27

L44	3	"6033787".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 15:46
L45	16	("4770953" | "5011732" | "5130498" | "5145540" | "5213877" | "5529852" | "5616421" | "5675474").PN. OR ("6033787"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/01 16:07
L46	4	l41 and brazing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 16:52
L47	4	l41 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 16:52
L48	10	("20040022029" "6310775" "6483185" "6563709" "20020125505").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:08
S65	93	("5556694" "5309122" "4917963" "4988641" "5209798" "5262794" "5416971" "5472914" "5764485" "5917157" "5936261" "6018187" "6040618" "6114739" "6133065" "6188391" "6215135" "6215164" "6215135" "6215164" "6229191" "4375054" "4863766" "4863808" "4961806" "4999585" "5214571" "5243133" "5262590" "5288944" "5298687" "5450046" "5452171" "5466960" "5504023" "5510156" "5561322" "5576052" "5661089" "5733639" "5747877" "5850092" "5853888" "5886487" "5895243" "5909631" "5925916" "5925915" "5930662" "5948533").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 11:57

S66	104	("6057571" "6066881" "6085415" "6100144" "6111204" "6183067" "6222136" "6222136" "6232183" "4262399" "4272561" "4285780" "4291364" "4300115" "4304681" "4306925" "4417393" "4418470" "4424579" "4432007" "4432134" "4442507" "4449118" "4480288" "4487993" "4514583" "4517051" "4553048" "4554537" "4578344" "4581547" "4590095" "4591220" "4603426" "4615950" "4616245" "4618763" "4769345" "4786342" "4798974" "4801905" "4805683" "4808274" "4819560" "4827377" "4839707" "4860165" "4873615" H000707 "4880959").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:39
S67	99	("4904978" "4933735" "4949219" "4992849" "4992850" "4994302" "4999160" "4999734" "5027189" "5177027" "5177668" "5178934" "5179460" "5184021" "5189505" "5201974" "5214322" "5221418" "5232548" "5240874" "5256588" "5261154" "5263248" "5264383" "5266512" "5272104" "5291438" "5295838" "5296722" "5296725" "5303862" "5321292" "5321380" "5345038" "5346401" "5354955" "5396397" "5406125" "5407851" "5442237" "5457336" "5463530" "5470787" "5476819" "5478757" "5482735" "5486656" "5488394" "5493096" "5496763").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:39
S68	102	("5497023" "5497545" "5503285" "5504372" "5509410" "5510654" "5528819" "5561303" "5578528" "5579207" "5581098" "5585624" "5587259" "5591676" "5599747" "5599744" "5601672" "5610790" "5609948" "5618777" "5619060" "5621193" "5637117" "5637834" "5644207" "5648806" "5650199" "5650246" "5650639" "5656395" "5661267" "5679436" "5686341" "5687479" "5694147" "5701020" "5707898" "5717247" "5719073" "5724232" "5726471" "5727548" "5736764" "5753976" "5766970" "5766996" "5796164" "5798909" "5798903" "5800724").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:40

S69	98	("5801448" "5812375" "5811869" "5817530" "5820551" "5831474" "5832599" "5835141" "5840199" "5846849" "5847936" "5850042" "5848837" "5851868" "5856235" "5859457" "5864261" "5891205" "5903050" "5908308" "5914534" "5915756" "5918153" "5922212" "5925298" "5933729" "5936159" "5946553" "5948193" "5953594" "5952716" "5955757" "5963788" "5962919" "5969922" "5974661" "5982250" "5985719" "5989934" "5993945" "5998237" "6002179" "6002951" "6018326" "6020624" RE36538 "6022670" "6023028" "6023408" "6030901").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:40
S70	90	("6038137" "6039889" "6048772" "6051866" "6057187" "6063678" "6074949" "6074916" "6078088" "6080668" "6094161" "6096565" "6100178" "6110789" "6110650" "6114986" "6124169" "6127231" "6130477" "6150207" "6153508" "6162683" "6165596" "6168725" "6190978" "6191451" "6197614" "6207354" "6208031" "6211022" "6218282" "6218290" "6221694" "6224965" "6225028" "6225670" "6211022" "6218282" "6218290" "6221694" "6224965" "6225028" "6225670" "6239494" "6245658" "6246118" "3700977" "3645783" "3640853" "3909726").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:41
S71	577	S65 S66 S67 S68 S69 S70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 18:41
S72	761	A1N	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 10:00
S73	121	S72 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 10:08

S74	1	copper with ((crystal adj particle adj diameter) near5 mm)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 10:13
S75	372	copper same (crystal$4 adj particle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 11:14
S76	258	S75 and heat$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 10:14